

a semiconductor die mounted on the substrate, the semiconductor die being electrically connected to a portion of the metallization layer;

a shield element mounted on the substrate, the shield element being electrically connected to a portion of the metallization layer; and

a package mold surrounding the semiconductor die and the shield element.

12. The semiconductor chip package of claim 11, wherein the metallization layer comprises:

a die pad formed on the substrate; and

a plurality of bond fingers formed on the substrate;

wherein the semiconductor die is attached to the die pad; and

wherein the shield element is attached to at least one of the bond fingers.

13. The semiconductor chip package of claim 12, further comprising a bond wire forming an electrical connection between a bond pad on the semiconductor die and one of the bond fingers.

14. The semiconductor chip package of claim 11 wherein the shield element comprises:

a substantially planar top surface; and

a plurality of substantially planar side surfaces, the side surfaces being joined to the top surface and to each other with rounded corners.

15. The semiconductor chip package of claim 11 wherein the shield element comprises:

a horizontal top surface; and

at least one vertical side surface, the side surface being joined to the top surface with a rounded corner.

16. The semiconductor chip package of claim 15 wherein the shield element comprises a plurality of openings formed in the top and side surfaces.

17. The semiconductor chip package of claim 15 wherein the top surface of the shield element is circular in shape.

18. The semiconductor chip package of claim 12 wherein the shield element comprises a plurality of legs attached to a corresponding plurality of the bond fingers.

19. The semiconductor chip package of claim 12 wherein at least one the legs of the shield element comprises a concave lower surface shaped to receive a corresponding one of the bond fingers.

20. (Amended) The semiconductor chip package of claim 12 wherein at least one of the legs of the shield element comprises a convex lower surface, and wherein a corresponding one of the bond fingers comprises a concave upper surface shaped to receive the convex lower surface of the leg.

21. A shielded semiconductor device package comprising:

a substrate having a metallization pattern formed on one side of the substrate, the metallization pattern having a plurality of solderable surface mount pads;

a semiconductor device electrically attached to the metallization pattern and mechanically attached to the substrate;

a metal screen enclosing the semiconductor device and electrically and mechanically attached to a portion of the metallization pattern to shield the semiconductor device from radio frequency energy; and

an insulating material transfer molded about the semiconductor device and encapsulating the metal screen.

Please add the following new claims 22-31.

22. (New) The shielded semiconductor device package of claim 21, wherein the metallization pattern comprises:

a die pad formed on the substrate; and

a plurality of bond fingers formed on the substrate;

wherein the semiconductor die is attached to the die pad; and

wherein the shield element is attached to at least one of the bond fingers.

23. (New) The shielded semiconductor device package of claim 21, wherein the metal screen comprises:

a substantially planar top surface; and

a plurality of substantially planar side surfaces, the side surfaces being joined to the top surface and to each other with rounded corners.

24. (New) The shielded semiconductor device package of claim 21, further comprising solder balls disposed on a side of the substrate opposite the metallization pattern and electrically coupled to the metallization pattern through the substrate.

25. (New) The shielded semiconductor device package of claim 21, further comprising solder balls disposed on a same side of the substrate as the metallization pattern and electrically coupled to the metallization pattern.

26. (New) The shielded semiconductor device package of claim 21, the metal screen comprises a plurality of legs attached to a corresponding plurality of the bond fingers.

27. (New) The shielded semiconductor chip package of claim 26 wherein at least one of the legs of the metal screen comprises a concave lower surface shaped to receive a corresponding bond finger.

28. (New) The shielded semiconductor chip package of claim 26 wherein at least one of the legs of the metal screen comprises a convex lower surface, and wherein a corresponding bond finger comprises a concave upper surface shaped to receive the convex lower surface of the leg.

29. (New) A semiconductor chip package comprising:

a substrate having first and second sides;

a metallization layer formed the first side of the substrate only, with no metallization layer being formed on the second side of the substrate;

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a semiconductor die mounted on the substrate, the semiconductor die being electrically connected to a portion of the metallization layer;

a shield element mounted on the substrate, the shield element being electrically connected to a portion of the metallization layer.

30. (New) The semiconductor chip package of claim 29, wherein the metallization layer comprises:

a die pad formed on the substrate; and
a plurality of bond fingers formed on the substrate;
wherein the semiconductor die is attached to the die pad; and
wherein the shield element is attached to at least one of the bond fingers.

31. (New) The semiconductor chip package of claim 29, further comprising solder balls disposed on the first side of the substrate and electrically coupled to the metallization pattern.

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